

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1657cgn#trpbf

(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.174411

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.005951 | 1000000 | 34120.5664062 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.063999 | 975000 | 366943.71875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001575 | 24000 | 9030.39746094 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000020 | 300 | 114.671707153 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000046 | 700 | 263.744934082 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.065640 | 1000000 | 376352.5625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.003749 | 1000000 | 21494.8183594 | | |
| | | External Plating Total: | | | | 0.003749 | 1000000 | 21494.8183594 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000525 | 1000000 | 3010.13208008 | | |
| | | Internal Plating Total: | | | | 0.000525 | 1000000 | 3010.13208008 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001496 | 750000 | 8577.44335938 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000499 | 250000 | 2861.05932617 | | |
| Die Attach Total: | | | | 0.001995 | 1000000 | 11438.5029297 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.009848 | 103000 | 56464.34375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.085571 | 895000 | 490628.625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000191 | 2000 | 1095.11474609 | | |
| | | Encapsulation Total: | | | | 0.095610 | 1000000 | 548188.0625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000941 | 1000000 | 5395.30371094 | | |
| | | | | | TOTAL MASS (g) : | 0.174411 | | |